

Electronic Patent Application Fee Transmittal

Application Number:	10608605
Filing Date:	27-Jun-2003
Title of Invention:	PACKAGING DEVICE FOR SEMICONDUCTOR DIE, SEMICONDUCTOR DEVICE INCORPORATING SAME AND METHOD OF MAKING SAME
First Named Inventor/Applicant Name:	Kong Weng Lee
Filer:	Scott Weitzel/Adrienne Barclay
Attorney Docket Number:	70030259-1

Filed as Large Entity

Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1400	1400
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1700